Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]
HP Compaq LE2001wm LCD Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>2</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Hand</td>
</tr>
<tr>
<td>Description #2</td>
<td>Slotted Screwdriver</td>
</tr>
<tr>
<td>Description #3</td>
<td>Philips Screwdriver</td>
</tr>
<tr>
<td>Description #4</td>
<td>Hex Socket Screwdriver</td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. 
2. 
3. 
4. 
5. 
6. 
7. 
8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
The Disassembly Procedure

LE2001wl Disassembly Diagram
1. Remove screws (4 pcs).
2. Remove Base assembly.
3. Remove screws (4 pcs).
4. Remove Bucket.
5. Remove Panel and Chassis.
6. Remove Buttons and Lens.
7. Separate Panel and Chassis.
8. Remove Screws (2 pcs).
9. Remove Screws (6 pcs).
10. Remove Main Board and Power Board.
11. Remove Neck Assembly.
12. Remove Screws (4 pcs) and Rubber (7 pcs).
13. Remove Bracket.
14. Remove Screws (3 pcs).
15. Remove VESA Bracket and Hinge Cover.
16. Remove ARM BACK.
17. Remove Screws (4 pcs).
18. Remove Hinge Assembly.
Technical Notification

Subject: WLED Disassembly Method
Customer: All
Product: LTM200KT07, LTM215HT03, LTM230HT05

Mar. 19, 2010

Application Engineering Part1
LCD Division
Samsung Electronics Co., Ltd.
WLED _ Disassembly Method

**Requires**
1. WLED Module - 1ea
2. Crossed Screw Driver - 1ea (any size)
3. Slotted Screwdriver or any flat thing - 1ea

**Disassembly**

1. Removing a Shield case
2. Removing a Top Chassis
3. Taking a panel apart from the Mold frame. (Silicon fixing, but can take off a panel easily.)
4. Taking a Mold frame off
WLED _ Disassembly Method

Removing Sheets

Removing Sheets

Removing a LGP

Removing reflection sheet

Disassemble LED Bar & Bottom Chassis.

LED Bar is fixed with a tape, so we need to take off well with any flat things.

Finish! Getting a LED Bar